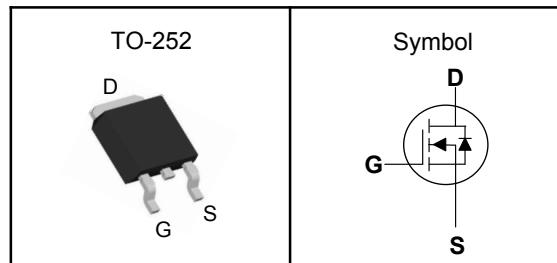


## 650V Super Junction Power MOSFET

### Features

- Low drain-source on-resistance:  $R_{DS(ON)}=0.55\Omega(\text{typ})$
- Easy to control gate switching
- Enhancement mode:  $V_{th} = 2.5 \text{ to } 4.5\text{V}$
- 100% avalanche tested
- RoHS compliant

### Pin Description



### Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger, Lighting

$V_{DSS}$	650	V
$R_{DS(ON)-\text{Typ}}$	550	$\text{m}\Omega$
$I_D$	8	A

### Absolute Maximum Ratings ( $T_J=25^\circ\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-Source Voltage	650	V
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$T_J$	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$E_{AS}$	Single Pulse Avalanche Energy <sup>③</sup>	156	mJ
$I_{DM}^{①}$	Pulse Drain Current Tested	24	A
$I_D$	Continuous Drain Current	$T_c=25^\circ\text{C}$	8
$P_D$	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	69
			W

### Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sub>1</sub>	1.8	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature  $150^\circ\text{C}$ .

Note ③ : Surface Mounted on 1in<sup>2</sup> FR-4 board with 1oz.

## 650V Super Junction Power MOSFET

### Electrical Characteristics ( $T_J=25^\circ\text{C}$ , Unless Otherwise Noted)

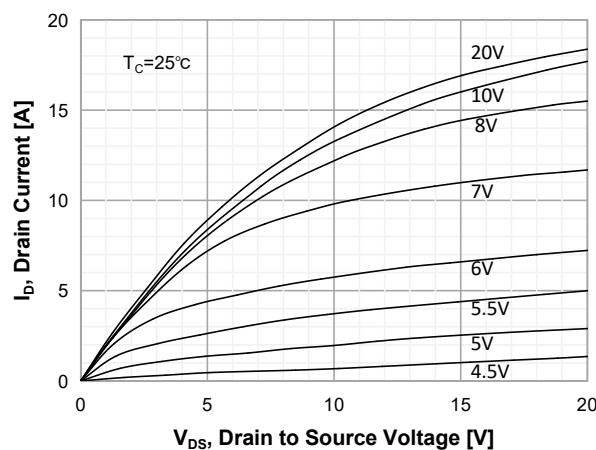
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	650	---	---	V
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=600\text{V}$ , $V_{\text{GS}}=0\text{V}$	---	---	1	$\mu\text{A}$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	2.5	---	4.5	V
$\text{I}_{\text{GSS}}$	Gate Leakage Current	$V_{\text{GS}}=\pm 30\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$
$\text{R}_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=2.5\text{A}$	---	550	600	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>⑤</sup></b>						
$\text{C}_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=400\text{V}$ , Freq.=1MHz	---	383	---	pF
$\text{C}_{\text{oss}}$	Output Capacitance		---	20	---	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	---	---	
$\text{T}_{\text{d(on)}}$	Turn-on Delay Time	$\text{V}_{\text{DD}}=400\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $R_{\text{G}}=10\Omega$ , $I_D=2.5\text{A}$	---	6	---	nS
$\text{T}_r$	Turn-on Rise Time		---	7	---	
$\text{T}_{\text{d(off)}}$	Turn-off Delay Time		---	26	---	
$\text{T}_f$	Turn-off Fall Time		---	13	---	
$\text{R}_g$	Gate Resistance	$f = 1.0\text{MHz}$ , open drain	---	0.7	---	$\Omega$
$\text{Q}_g$	Total Gate Charge	$\text{V}_{\text{DS}}=400\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $I_D=2.5\text{A}$	---	10	---	nC
$\text{Q}_{\text{gs}}$	Gate-Source Charge		---	2.1	---	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		---	4.9	---	
<b>Source-Drain Characteristics (<math>T_J=25^\circ\text{C}</math>)</b>						
$\text{V}_{\text{SD}}^{④}$	Diode Forward Voltage	$I_S=2.5\text{A}$ , $V_{\text{GS}}=0\text{V}$	---	---	1.2	V
$\text{t}_{\text{rr}}$	Reverse Recovery Time	$\text{V}_{\text{R}}=400\text{V}$ , $I_F=2.5\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	173	---	nS
$\text{Q}_{\text{rr}}$	Reverse Recovery Charge		---	1.1	---	nC

Note ④ : Pulse test (pulse width $\leq 300\text{us}$ , duty cycle $\leq 2\%$ ).

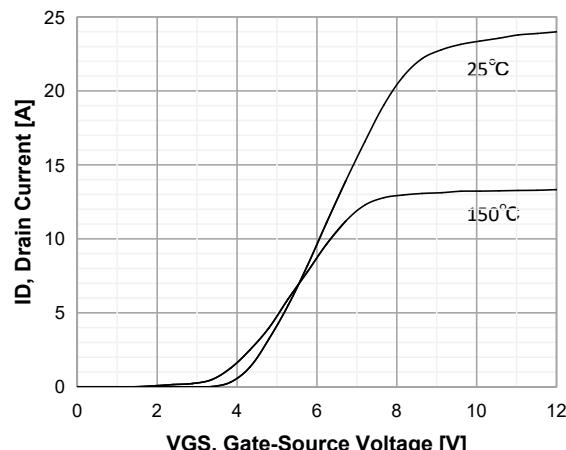
Note ⑤ : Guaranteed by design, not subject to production testing.

## 650V Super Junction Power MOSFET

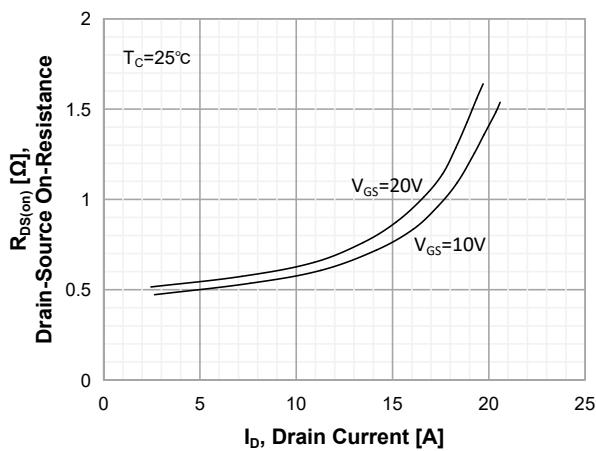
### Typical Characteristics



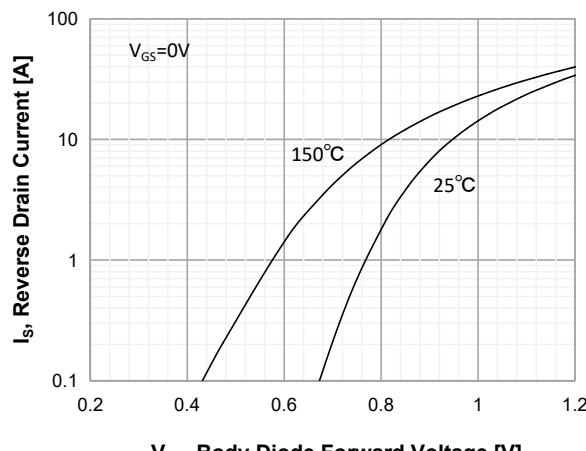
**Figure 1. On-Region Characteristics**



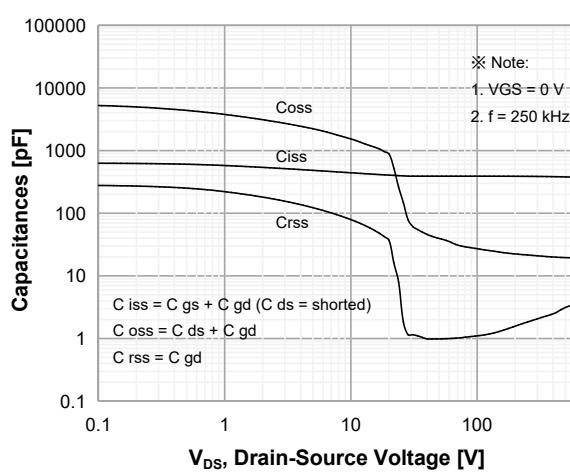
**Figure 2. Transfer Characteristics**



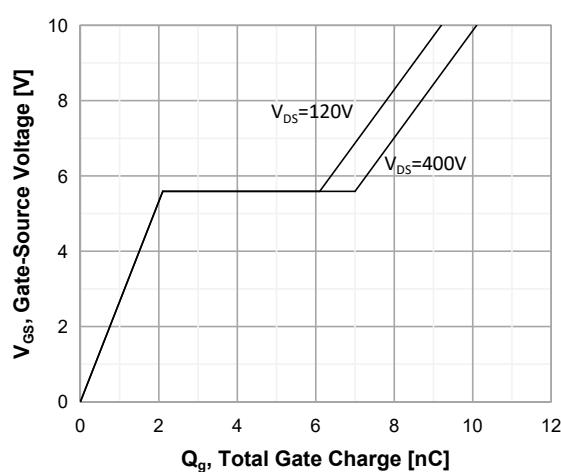
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

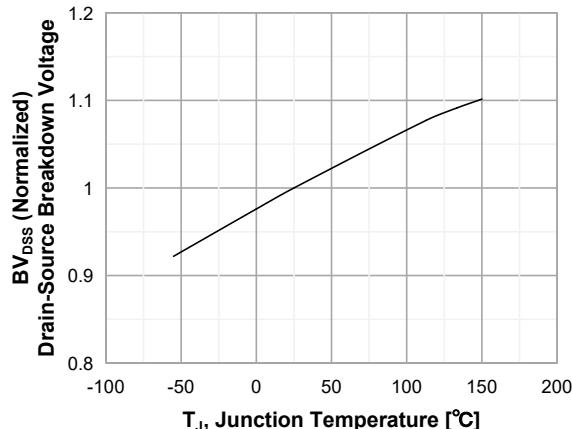


**Figure 5. Capacitance Characteristics**

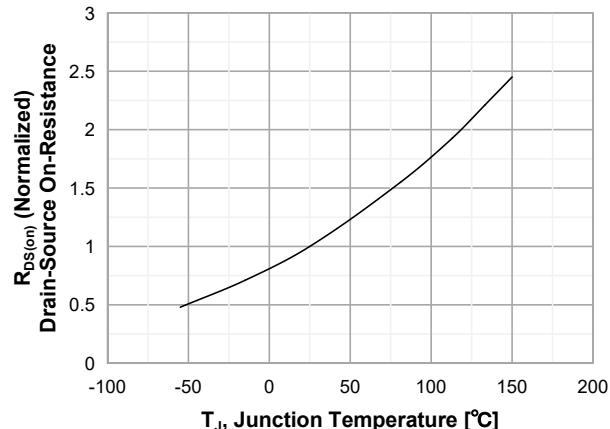


**Figure 6. Gate Charge Characteristics**

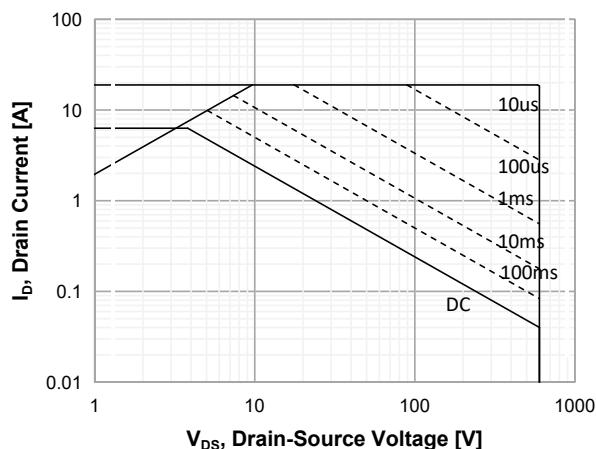
## 650V Super Junction Power MOSFET



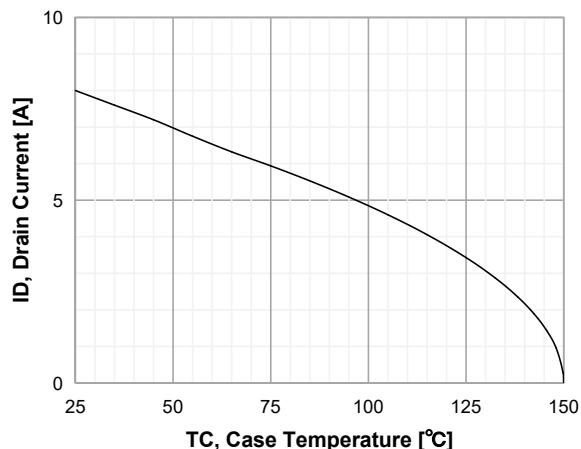
**Figure 7. Breakdown Voltage Variation vs Temperature**



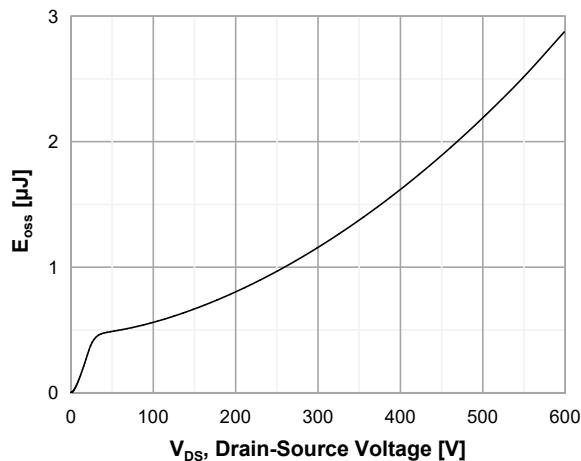
**Figure 8. On-Resistance Variation vs Temperature**



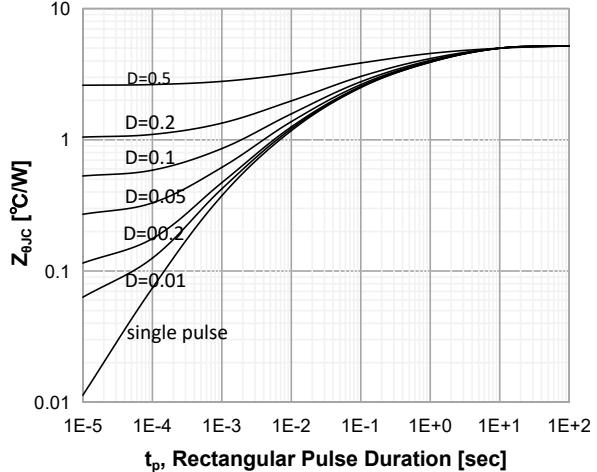
**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**



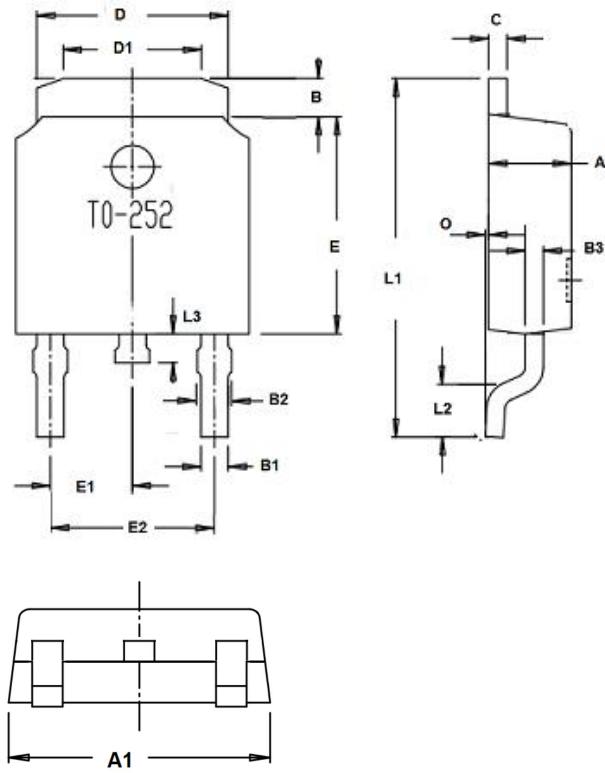
**Figure 11.  $E_{oss}$  vs. Drain to Source Voltage**



**Figure 12. Transient Thermal Response Curve**

## 650V Super Junction Power MOSFET

### TO-252 Package Outline Dimensions



Dim.	Min.	Max.
A	2.1	2.5
A1	6.3	6.9
B	0.96	1.42
B1	0.74	0.86
B2	0.74	0.94
C	Typ0.5	
D	5.33	5.53
D1	3.65	4.05
E	6.0	6.2
E1	Typ2.29	
E2	Typ4.58	
O	0	0.15
L1	9.9	10.5
L2	Typ1.65	
L3	0.6	1.0
All Dimensions in millimeter		